



ZXMP3A13F

30V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	Max R _{DS(ON)}	Package	Max I _D T _A = +25°C
-30V	0.21Ω @ V _{GS} = -10V	SOT23	-1.6A
-307	0.33Ω @ V _{GS} = -4.5V	30123	-1.1A

Features

- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description

This new generation of trench MOSFETs utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, and power management applications.

Applications

- DC-DC Converters
- Power Management Functions
- Disconnect Switches
- Motor Control

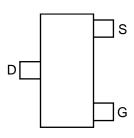
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 (2)
- Weight: 0.008 grams (Approximate)

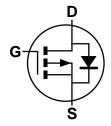
SOT23



Top View



Top View Pin Out



Equivalent Circuit

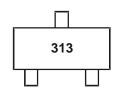
Ordering Information (Note 4)

Part Number	Compliance	Case	Quantity per Reel
ZXMP3A13FTA	Standard	SOT23	3,000
ZXMP3A13FTC	Standard	SOT23	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



313 = Product Type Marking Code



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic				Symbol	Value	Units
Drain-Source Voltage				V_{DSS}	-30	V
Gate-Source Voltage			V_{GS}	±20	V	
Continuous Drain Current	V _{GS} = 10V	T _A = +70°C	(Note 6) (Note 6) (Note 5)	I_{D}	-1.6 -1.3 -1.4	А
Pulsed Drain Current (Note 7)				I_{DM}	-6	A
Continuous Source Current (Body Diode) (Note 6)				Is	-1.2	A
Pulsed Source Current (Body Diode) (Note 7)				I _{SM}	-6	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) Linear Derating Factor	P _D	625 5	mW mW/°C
Power Dissipation (Note 6) Linear Derating Factor	P _D	806 6.4	mW mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	155	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

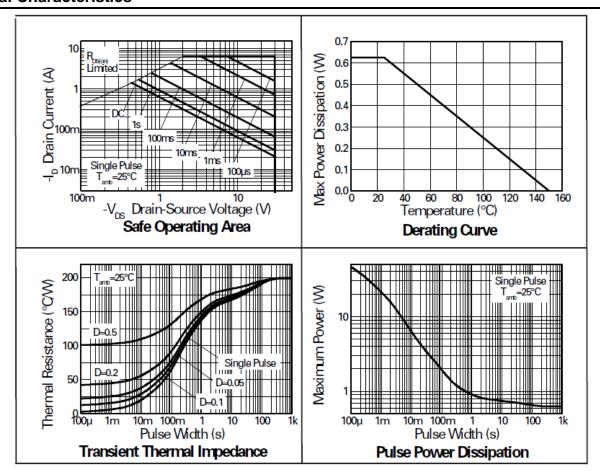
^{5.} For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

^{6.} For a device surface mounted on FR4 PCB measured at t ≤5 secs.

7. Repetitive rating 25mm x 25mm FR4 PCB, D=0.05 pulse width=10µs - pulse current limited by maximum junction temperature.



Thermal Characteristics





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

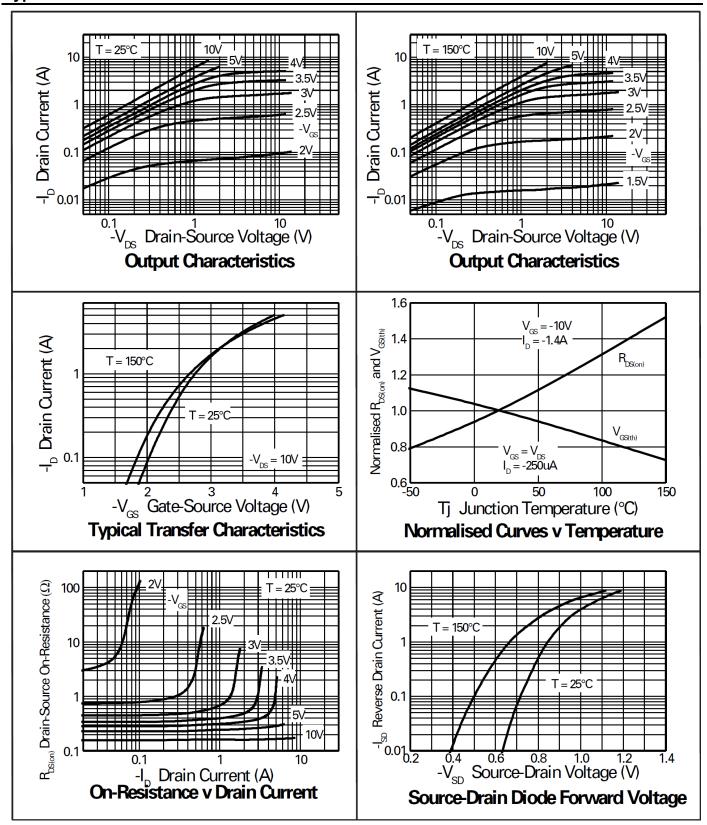
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	-30		_	٧	$I_D = -250\mu A, V_{GS} = 0V$
Zero Gate Voltage Drain Current		_	_	-0.5	μΑ	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(th)}$	-1.0	_	_	V	$I_D = -250 \mu A, V_{DS} = V_{GS}$
Static Drain-Source On-Resistance (Note 8)	D			0.21	Ω	$V_{GS} = -10V, I_D = -1.4A$
Static Dialit-Source Off-Resistance (Note 6)	R _{DS(ON)}	_	_	0.33		$V_{GS} = -4.5V, I_D = -1.1A$
Forward Transconductance (Notes 8 & 10)	g _{fs}	_	2.4	_	S	$V_{DS} = -15V, I_{D} = -1.4A$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C _{iss}	_	206	_		\/ 45\/\\ 0\/
Output Capacitance	Coss	_	59.3		pF	$V_{DS} = -15V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	49.2	_		I = 1.0WHZ
SWITCHING (Notes 9 & 10)						
Turn-On Delay Time	t _{d(ON)}	_	1.5	_		
Rise Time	t _R	_	3.0	_	nS	$V_{DD} = -15V, I_{D} = -1.0A,$
Turn-Off Delay Time	t _{D(OFF)}	_	11.1		113	$R_G\cong 6.0\Omega,\ V_{GS}=\text{-}10V$
Fall Time	t _f	_	7.6	_		
Gate Charge	Qg	_	3.8	_	nC	$V_{DS} = -15V$, $V_{GS} = -5.0V$, $I_{D} = -1.4A$
Total Gate Charge	Qq		6.4	_		V _{DS} = -15V, V _{GS} = -10V, I _D = -1.4A
Gate-Source Charge	Q _{qs}	_	0.69	_	nC	
Gate-Drain Charge	Q_{gd}	_	2.0	_		
SOURCE-DRAIN DIODE						
Diode Forward Voltage (Note 8)	V_{SD}	_	-0.85	-0.95	V	$T_J = +25^{\circ}C$, $I_S = -1.1A$, $V_{GS} = 0V$
Reverse Recovery Time (Note 10)	t _{RR}	_	15.6	_	nS T _{.I} = +25°C, I _E = -0.95A,	
Reverse Recovery Charge (Note 10)	Q _{RR}	_	9.6	_	nC	di/dt = 100A/µs

Notes:

^{8.} Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤ 2%.
9. Switching characteristics are independent of operating junction temperature.
10. For design aid only, not subject to production testing.

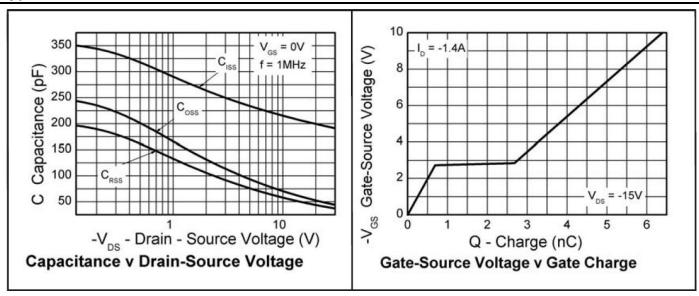


Typical Characteristics

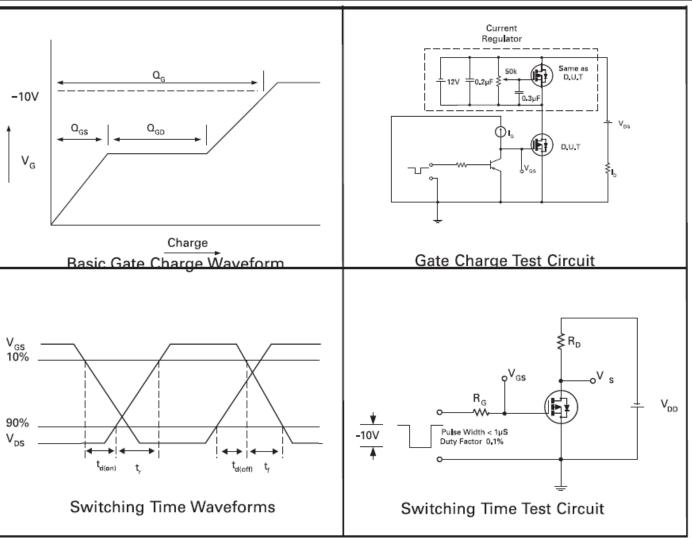




Typical Characteristics (Continued)



Test Circuits

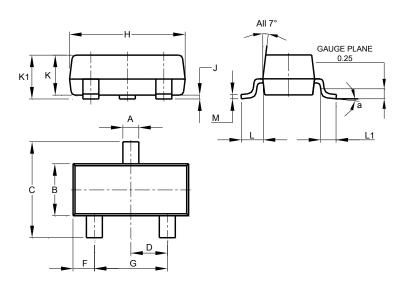




Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

SOT23

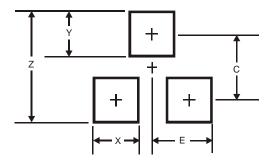


SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
K	0.890	1.00	0.975		
K1	0.903	1.10	1.025		
L	0.45	0.61	0.55		
L1	0.25	0.55	0.40		
M	0.085	0.150	0.110		
а	8°				
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

SOT23



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
С	2.0
E	1.35



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